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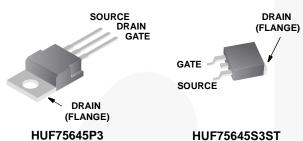
Data Sheet October 2013

N-Channel UltraFET Power MOSFET 100 V, 75 A, 14 mΩ

Packaging

JEDEC TO-220AB

JEDEC TO-263AB



HUF75645S3ST

Features

- Ultra Low On-Resistance
 - $r_{DS(ON)} = 0.014\Omega$, $V_{GS} = 10V$
- Simulation Models
 - Temperature Compensated PSPICE® and SABER™ **Electrical Models**
 - Spice and Saber Thermal Impedance Models
 - www.fairchildsemi.com
- · Peak Current vs Pulse Width Curve
- · UIS Rating Curve

Ordering Information

PART NUMBER	PACKAGE	BRAND
HUF75645P3	TO-220AB	75645P
HUF75645S3ST	TO-263AB	75645S

Symbol



Absolute Maximum Ratings $T_C = 25^{\circ}C$, Unless Otherwise Specified		
	HUF75645P3, HUF75645S3ST	UNITS
Drain to Source Voltage (Note 1)	100	V
Drain to Gate Voltage ($R_{GS} = 20k\Omega$) (Note 1)	100	V
Gate to Source Voltage	±20	V
Drain Current		
Continuous (T _C = 25 ^o C, V _{GS} = 10V) (Figure 2)	75	Α
Continuous (T_C = 100°C, V_{GS} = 10V) (Figure 2)	65	Α
Pulsed Drain Current	Figure 4	
Pulsed Avalanche Rating	Figures 6, 14, 15	
Power Dissipation	310	W
Derate Above 25°C	2.07	W/oC
Operating and Storage Temperature	-55 to 175	°C
Maximum Temperature for Soldering		
Leads at 0.063in (1.6mm) from Case for 10sTL	300	°C
Package Body for 10s, See Techbrief TB334	260	°C
NOTES:		

1. $T_{.J} = 25^{\circ}C$ to $150^{\circ}C$.

CAUTION: Stresses above those listed in "Absol24ute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

Product reliability information can be found at http://www.fairchildsemi.com/products/discrete/reliability/index.html For severe environments, see our Automotive HUFA series.

All Fairchild semiconductor products are manufactured, assembled and tested under ISO9000 and QS9000 quality systems certification.

HUF75645P3, HUF75645S3S

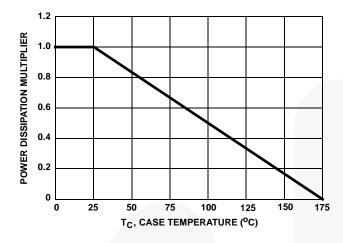
Electrical Specifications $T_C = 25^{\circ}C$, Unless Otherwise Specified

PARAMETER	SYMBOL	TES.	T CONDITIONS	MIN	TYP	MAX	UNITS
OFF STATE SPECIFICATIONS		1		"		l	
Drain to Source Breakdown Voltage	BV _{DSS}	I _D = 250μA, V _{GS} = 0V (Figure 11)		100	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 95V, V_{GS} = 0$	V	-	-	1	μΑ
		$V_{DS} = 90V, V_{GS} = 0V, T_{C} = 150^{\circ}C$		-	-	250	μА
Gate to Source Leakage Current	I _{GSS}	V _{GS} = ±20V		-	-	±100	nA
ON STATE SPECIFICATIONS							
Gate to Source Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_D = 250$	0μA (Figure 10)	2	-	4	V
Drain to Source On Resistance	r _{DS(ON)}	I _D = 75A, V _{GS} = 10V (Figure 9)		-	0.0115	0.014	Ω
THERMAL SPECIFICATIONS	. 1						
Thermal Resistance Junction to Case	$R_{\theta JC}$	TO-220 and TO-263		-	-	0.48	oC/W
Thermal Resistance Junction to Ambient	$R_{\theta JA}$			-	-	62	°C/W
SWITCHING SPECIFICATIONS (VGS =	= 10V)	1					1
Turn-On Time	tON	$V_{DD} = 50V, I_{D} = 75A$ $V_{GS} = 10V,$ $R_{GS} = 2.5\Omega$ (Figures 18, 19)		-	-	197	ns
Turn-On Delay Time	t _d (ON)			-	14	-	ns
Rise Time	t _r			-	117	-	ns
Turn-Off Delay Time	t _d (OFF)			-	41	-	ns
Fall Time	t _f			_	97	-	ns
Turn-Off Time	tOFF			-	-	207	ns
GATE CHARGE SPECIFICATIONS	1						
Total Gate Charge	Q _{g(TOT)}	V _{GS} = 0V to 20V	V _{DD} = 50V,	-	198	238	nC
Gate Charge at 10V	Q _{g(10)}	V _{GS} = 0V to 10V	$ I_D = 75A, I_{g(REF)} = 1.0mA$	/ -	106	127	nC
Threshold Gate Charge	Q _{g(TH)}	V _{GS} = 0V to 2V	(Figures 13, 16, 17)	-	6.8	8.2	nC
Gate to Source Gate Charge	Q _{gs}			-	14	-	nC
Gate to Drain "Miller" Charge	Q _{gd}			-	41	-	nC
CAPACITANCE SPECIFICATIONS				1		1	
Input Capacitance	C _{ISS}	f = 1MHz (Figure 12) - 81		-	3790	-	pF
Output Capacitance	C _{OSS}			810	-	pF	
Reverse Transfer Capacitance	C _{RSS}			-	230	-	pF

Source to Drain Diode Specifications

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Source to Drain Diode Voltage	V_{SD}	I _{SD} = 75A	-	-	1.25	V
		I _{SD} = 35A	-	-	1.00	V
Reverse Recovery Time	t _{rr}	I _{SD} = 75A, dI _{SD} /dt = 100A/μs	-	-	145	ns
Reverse Recovered Charge	Q _{RR}	$I_{SD} = 75A$, $dI_{SD}/dt = 100A/\mu s$	-	-	360	nC

Typical Performance Curves



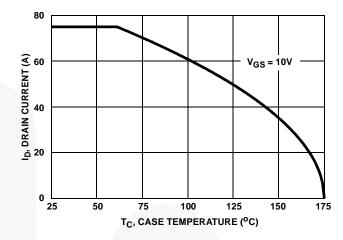


FIGURE 1. NORMALIZED POWER DISSIPATION vs CASE TEMPERATURE

FIGURE 2. MAXIMUM CONTINUOUS DRAIN CURRENT vs CASE TEMPERATURE

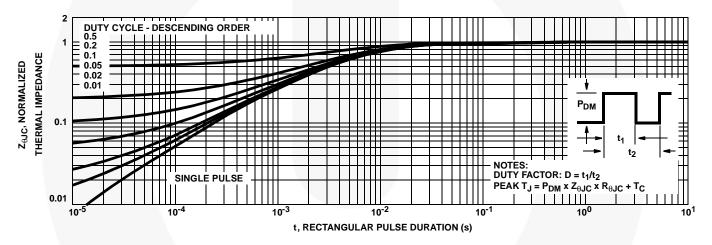


FIGURE 3. NORMALIZED MAXIMUM TRANSIENT THERMAL IMPEDANCE

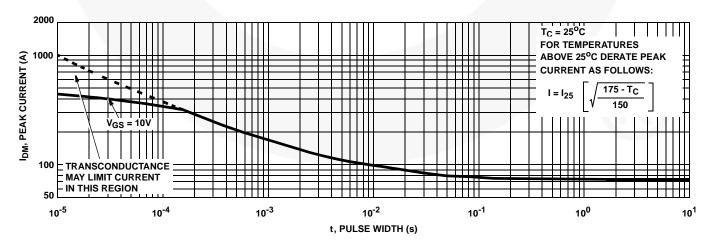


FIGURE 4. PEAK CURRENT CAPABILITY

Typical Performance Curves (Continued)

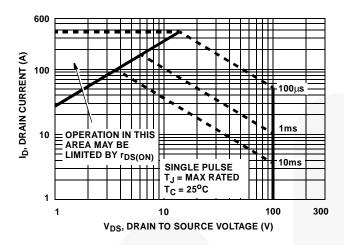


FIGURE 5. FORWARD BIAS SAFE OPERATING AREA

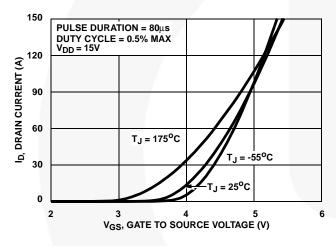


FIGURE 7. TRANSFER CHARACTERISTICS

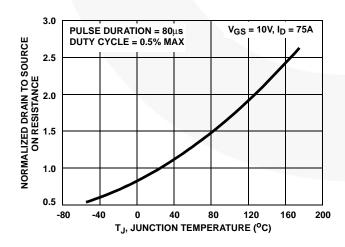
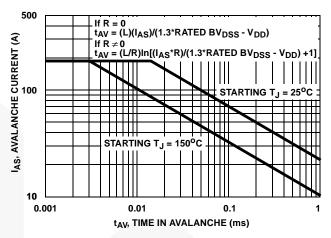


FIGURE 9. NORMALIZED DRAIN TO SOURCE ON RESISTANCE vs JUNCTION TEMPERATURE



NOTE: Refer to Fairchild Application Notes AN9321 and AN9322.

FIGURE 6. UNCLAMPED INDUCTIVE SWITCHING CAPABILITY

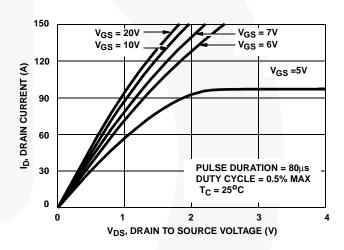


FIGURE 8. SATURATION CHARACTERISTICS

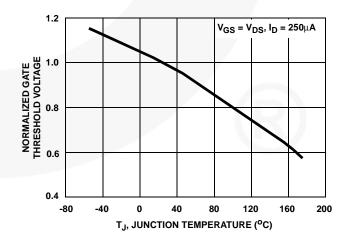
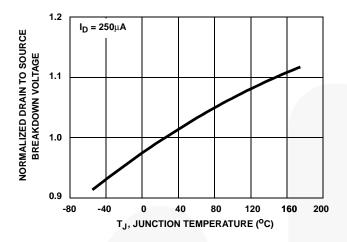


FIGURE 10. NORMALIZED GATE THRESHOLD VOLTAGE vs JUNCTION TEMPERATURE

Typical Performance Curves (Continued)



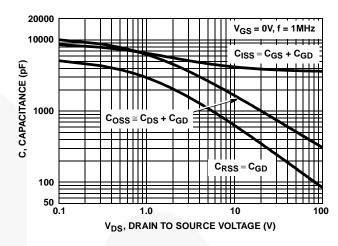
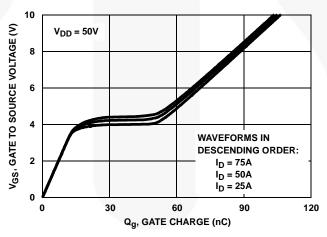


FIGURE 11. NORMALIZED DRAIN TO SOURCE BREAKDOWN VOLTAGE vs JUNCTION TEMPERATURE

FIGURE 12. CAPACITANCE vs DRAIN TO SOURCE VOLTAGE



NOTE: Refer to Fairchild Application Notes AN7254 and AN7260.

FIGURE 13. GATE CHARGE WAVEFORMS FOR CONSTANT GATE CURRENT

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Test Circuits and Waveforms

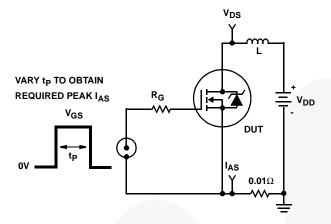


FIGURE 14. UNCLAMPED ENERGY TEST CIRCUIT

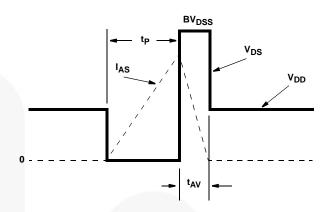


FIGURE 15. UNCLAMPED ENERGY WAVEFORMS

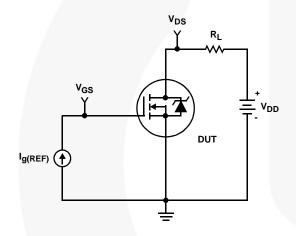


FIGURE 16. GATE CHARGE TEST CIRCUIT

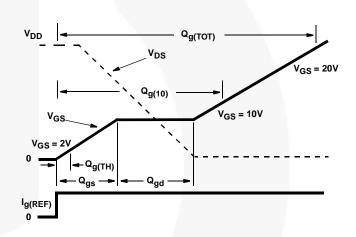


FIGURE 17. GATE CHARGE WAVEFORMS

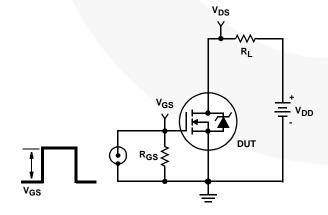


FIGURE 18. SWITCHING TIME TEST CIRCUIT

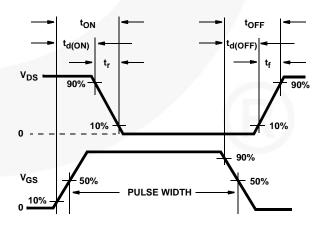
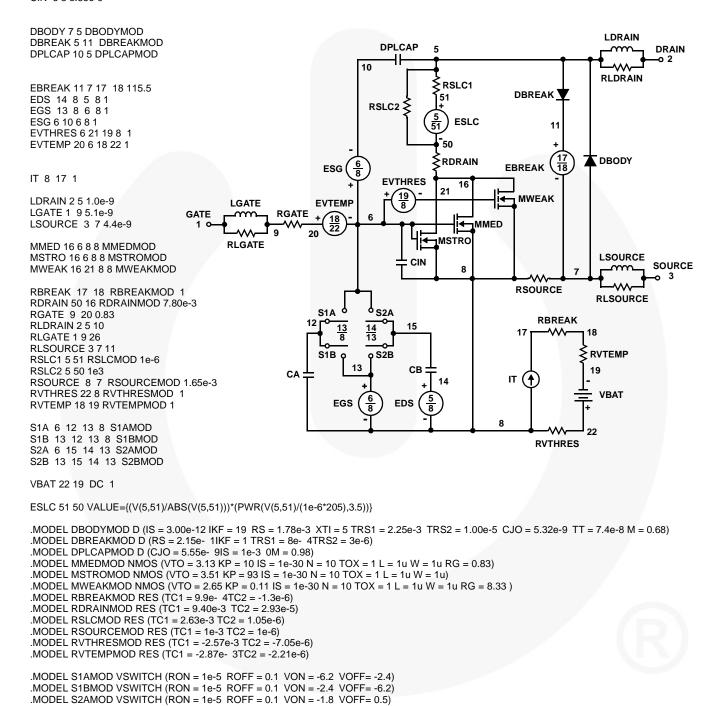


FIGURE 19. SWITCHING TIME WAVEFORM

PSPICE Electrical Model

.SUBCKT HUF75645 2 1 3; rev 21 May 1999

CA 12 8 5.31e-9 CB 15 14 5.31e-9 CIN 6 8 3.56e-9



.ENDS

NOTE: For further discussion of the PSPICE model, consult **A New PSPICE Sub-Circuit for the Power MOSFET Featuring Global Temperature Options**; IEEE Power Electronics Specialist Conference Records, 1991, written by William J. Hepp and C. Frank Wheatley.

.MODEL S2BMOD VSWITCH (RON = 1e-5 ROFF = 0.1 VON = 0.5 VOFF= -1.8)

SABER Electrical Model

```
REV 21 May 1999
template ta75645 n2,n1,n3
electrical n2,n1,n3
var i iscl
d..model dbodymod = (is = 3.00e-12, cjo = 5.32e-9, tt = 7.4e-8, xti = 5, m = 0.68)
d..model dbreakmod = ()
d..model dplcapmod = (cjo = 5.55e-9, is = 1e-30, vj=1.0, m = 0.8)
m..model mmedmod = (type=_n, vto = 3.13, kp = 10, is = 1e-30, tox = 1)
m..model mstrongmod = (type=_n, vto = 3.51, kp = 93, is = 1e-30, tox = 1)
m..model mweakmod = (type=_n, vto = 2.65, kp = 0.11, is = 1e-30, tox = 1)
                                                                                                                               LDRAIN
sw_vcsp..model s1amod = (ron = 1e-5, roff = 0.1, von = -6.2, voff = -2.4)
                                                                                 DPLCAP
                                                                                                                                          DRAIN
sw_vcsp..model s1bmod = (ron =1e-5, roff = 0.1, von = -2.4, voff = -6.2)
sw_vcsp..model s2amod = (ron = 1e-5, roff = 0.1, von = -1.8, voff = 0.5)
                                                                              10
                                                                                                                               RLDRAIN
sw_vcsp..model s2bmod = (ron = 1e-5, roff = 0.1, von = 0.5, voff = -1.8)
                                                                                              RSLC1
                                                                                                          RDBREAK
c.ca n12 n8 = 5.31e-9
                                                                               RSLC2 ≥
                                                                                                                   72
c.cb n15 n14 = 5.31e-9
                                                                                                                               RDBODY
                                                                                                ISCL
c.cin n6 n8 = 3.56e-9
                                                                                                            DBREAK _
d.dbody n7 n71 = model=dbodymod
                                                                                              RDRAIN
d.dbreak n72 n11 = model=dbreakmod
                                                                           6
8
                                                                      ESG
                                                                                                                    11
d.dplcap n10 n5 = model=dplcapmod
                                                                                  EVTHRES
                                                                                                  16
                                                                                              21
                                                                                     \frac{19}{8}
                                                                                                              MWEAK
i.it n8 n17 = 1
                                                   LGATE
                                                                    EVTEMP
                                                                                                                               DBODY
                                                            RGATE
                                         GATE
                                                                                                              EBREAK
I.ldrain n2 n5 = 1e-9
                                                                                                    MMED
                                                                   20
I.lgate n1 n9 = 5.1e-9
                                                                                          I<del><</del>_MSTR
                                                  RLGATE
I.Isource n3 n7 = 4.4e-9
                                                                                                                               LSOURCE
                                                                                        CIN
                                                                                                                                         SOURCE
                                                                                                  8
m.mmed n16 n6 n8 n8 = model=mmedmod, l=1u, w=1u
m.mstrong n16 n6 n8 n8 = model=mstrongmod, l=1u, w=1u
                                                                                                             RSOURCE
m.mweak n16 n21 n8 n8 = model=mweakmod, l=1u, w=1u
                                                                                                                             RLSOURCE
                                                                               S2A
res.rbreak n17 n18 = 1, tc1 = 9.9e-4, tc2 = -1.3e-6
                                                                                                                  RBREAK
res.rdbody n71 n5 = 1.78e-3, tc1 = 2.25e-3, tc2 = 1.e-5
                                                                                                              17
res.rdbreak n72 n5 = 2.15e-1, tc1 = 8e-4, tc2 = 3e-6
                                                                                                                             RVTEMP
res.rdrain n50 n16 = 7.8e-3, tc1 = 9.4e-3, tc2 = 2.93e-5
                                                                               oS2B
res.rgate n9 n20 = 0.83
                                                                                       CB
                                                              CA
res.rldrain n2 n5 = 10
                                                                                                            ΙT
res.rlgate n1 n9 = 26
                                                                                                                               VBAT
res.rlsource n3 n7 = 11
                                                                        EGS
                                                                                    EDS
res.rslc1 n5 n51 = 1e-6, tc1 = 2.63e-3, tc2 = 1.05e-6
                                                                                                          8
res.rslc2 n5 n50 = 1e3
res.rsource n8 n7 = 1.65e-3, tc1 = 1e-3, tc2 = 1e-6
                                                                                                                 RVTHRES
res.rvtemp n18 n19 = 1, tc1 = -2.87e-3, tc2 = -2.21e-6
res.rvthres n22 n8 = 1, tc1 = -2.57e-3, tc2 = -7.05e-6
spe.ebreak n11 n7 n17 n18 = 115.5
spe.eds n14 n8 n5 n8 = 1
spe.egs n13 n8 n6 n8 = 1
spe.esg n6 n10 n6 n8 = 1
spe.evtemp n20 n6 n18 n22 = 1
spe.evthres n6 n21 n19 n8 = 1
sw_vcsp.s1a n6 n12 n13 n8 = model=s1amod
sw_vcsp.s1b n13 n12 n13 n8 = model=s1bmod
sw_vcsp.s2a n6 n15 n14 n13 = model=s2amod
sw_vcsp.s2b n13 n15 n14 n13 = model=s2bmod
v.vbat n22 n19 = dc=1
equations {
i (n51->n50) +=iscl
iscl: v(n51,n50) = ((v(n5,n51)/(1e-9+abs(v(n5,n51))))*((abs(v(n5,n51)*1e6/205))** 3.5))
```

SPICE Thermal Model

REV 28 July 1999

HUF75645T

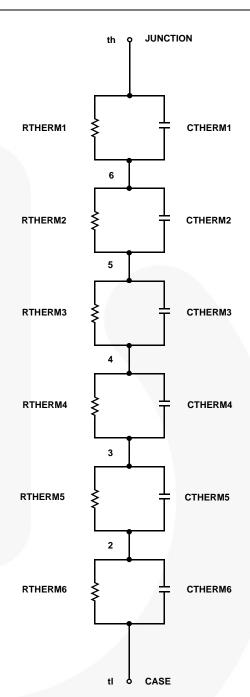
CTHERM1 th 6 8.80e-3
CTHERM2 6 5 2.50e-2
CTHERM3 5 4 2.70e-2
CTHERM4 4 3 3.70e-2
CTHERM5 3 2 4.40e-2
CTHERM6 2 tl 3.40e-1

RTHERM1 th 6 1.20e-2
RTHERM2 6 5 3.00e-2
RTHERM3 5 4 4.30e-2
RTHERM4 4 3 8.80e-2
RTHERM5 3 2 9.90e-2
RTHERM6 2 tl 1.10e-1

SABER Thermal Model

SABER thermal model HUF75645T

```
template thermal_model th tl thermal_c th, tl \{ ctherm.ctherm1 th 6=8.80e-3 ctherm.ctherm2 6.5=2.50e-2 ctherm.ctherm3 5.4=2.70e-2 ctherm.ctherm4 4.3=3.70e-2 ctherm.ctherm5 3.2=4.40e-2 ctherm.ctherm6 2.1=3.40e-1 rtherm.rtherm1 th 6=1.20e-2 rtherm.rtherm2 6.5=3.00e-2 rtherm.rtherm3 5.4=4.30e-2 rtherm.rtherm4 4.3=8.80e-2 rtherm.rtherm5 3.2=9.90e-2 rtherm.rtherm6 2.1=1.10e-1
```





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